To our customers,

Old Company Name in Catalogs and Other Documents

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Renesas Electronics website: http://www.renesas.com

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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RENESAS

MOS INTEGRATED CIRCUIT

μPD44164085A-A, 44164095A-A, 44164185A-A, 44164365A-A

18M-BIT DDRII SRAM SEPARATE I/O 2-WORD BURST OPERATION

Description

The μPD44164085A-A is a 2,097,152-word by 8-bit, the μPD44164095A-A is a 2,097,152-word by 9-bit, the μPD44164185A-A is a 1,048,576-word by 18-bit and the μPD44164365A-A is a 524,288-word by 36-bit synchronous double data rate static RAM fabricated with advanced CMOS technology using full CMOS six-transistor memory cell.

The μPD44164085A-A, μPD44164095A-A, μPD44164185A-A and μPD44164365A-A integrate unique synchronous peripheral circuitry and a burst counter. All input registers controlled by an input clock pair (K and K#) are latched on the positive edge of K and K#.

These products are suitable for application which require synchronous operation, high speed, low voltage, high density and wide bit configuration.

These products are packaged in 165-pin PLASTIC BGA.

Features

- 1.8 ± 0.1 V power supply
- 165-pin PLASTIC BGA package (13 x 15)
- HSTL interface
- PLL circuitry for wide output data valid window and future frequency scaling
- Separate independent read and write data ports
- DDR read or write operation initiated each cycle
- Pipelined double data rate operation
- Separate data input/output bus
- Two-tick burst for low DDR transaction size
- Two input clocks (K and K#) for precise DDR timing at clock rising edges only
- Two output clocks (C and C#) for precise flight time and clock skew matching-clock and data delivered together to receiving device
- Internally self-timed write control
- Clock-stop capability. Normal operation is restored in 1,024 cycles after clock is resumed.
- User programmable impedance output
- Fast clock cycle time : 3.3 ns (300 MHz), 3.7 ns (270 MHz), 4.0 ns (250 MHz), 5.0 ns (200 MHz)
- Simple control logic for easy depth expansion
- JTAG boundary scan
- Operating ambient temperature: Commercial T_A = 0 to +70°C (-E33, -E37, -E40, -E50)
  Industrial T_A = –40 to +85°C (-E37Y, -E40Y, -E50Y)

Document No. M19868EJ1V0DS00 (1st edition)
Date Published July 2009
Printed in Japan

Ordering Information

(1) Operating Ambient Temperature T_A = 0 to +70°C

Part number	Cycle Time ns	Clock Frequency MHz	Organization (word x bit)	Package	Operating Ambient Temperature
μPD44164085AF5-E33-EQ2-A	3.3	300	2M x 8-bit	165-pin PLASTIC BGA (13 x 15) Lead-free	Commercial (T_A = 0 to +70°C)
μPD44164085AF5-E40-EQ2-A	4.0	250			
μPD44164085AF5-E50-EQ2-A	5.0	200			
μPD44164095AF5-E33-EQ2-A	3.3	300	2M x 9-bit		
μPD44164095AF5-E40-EQ2-A	4.0	250			
μPD44164095AF5-E50-EQ2-A	5.0	200			
μPD44164185AF5-E33-EQ2-A	3.3	300	1M x 18-bit		
μPD44164185AF5-E37-EQ2-A	3.7	270			
μPD44164185AF5-E40-EQ2-A	4.0	250			
μPD44164185AF5-E50-EQ2-A	5.0	200			
μPD44164365AF5-E33-EQ2-A	3.3	300	512K x 36-bit		
μPD44164365AF5-E40-EQ2-A	4.0	250			
μPD44164365AF5-E50-EQ2-A	5.0	200			

Remarks 1. QDR Consortium standard package size is 13 x 15 and 15 x 17.

The footprint is commonly used.

2. Products with -A at the end of the part number are lead-free products.

(2) Operating Ambient Temperature T_A = –40 to +85°C

Part number	Cycle Time ns	Clock Frequency MHz	Organization (word x bit)	Package	Operating Ambient Temperature
μPD44164085AF5-E37Y-EQ2-A	3.7	270	2M x 8-bit	165-pin PLASTIC BGA (13 x 15) Lead-free	Industrial (T_A = –40 to +85°C)
μPD44164085AF5-E40Y-EQ2-A	4.0	250			
μPD44164085AF5-E50Y-EQ2-A	5.0	200			
μPD44164095AF5-E37Y-EQ2-A	3.7	270	2M x 9-bit		
μPD44164095AF5-E40Y-EQ2-A	4.0	250			
μPD44164095AF5-E50Y-EQ2-A	5.0	200			
μPD44164185AF5-E37Y-EQ2-A	3.7	270	1M x 18-bit		
μPD44164185AF5-E40Y-EQ2-A	4.0	250			
μPD44164185AF5-E50Y-EQ2-A	5.0	200			

Remarks 1. QDR Consortium standard package size is 13 x 15 and 15 x 17.

The footprint is commonly used.

2. Products with -A at the end of the part number are lead-free products.

Pin Configurations

165-pin PLASTIC BGA (13 x 15)

(Top View)

[μPD44164085A-A]

2M x 8-bit

	1	2	3	4	5	6	7	8	9	10	11
A	CQ#	V_{SS}	A	R, W#	NW1#	K#	NC	LD#	A	V_{SS}	CQ
B	NC	NC	NC	A	NC	K	NW0#	A	NC	NC	Q3
C	NC	NC	NC	V_{SS}	A	A	A	V_{SS}	NC	NC	D3
D	NC	D4	NC	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	NC	NC
E	NC	NC	Q4	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	D2	Q2
F	NC	NC	NC	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	NC
G	NC	D5	Q5	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	NC
H	DLL#	V_{REF}	$V_{DD}Q$	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	$V_{DD}Q$	V_{REF}	ZQ
J	NC	NC	NC	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	Q1	D1
K	NC	NC	NC	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	NC
L	NC	Q6	D6	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	NC	Q0
M	NC	NC	NC	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	NC	D0
N	NC	D7	NC	V_{SS}	A	A	A	V_{SS}	NC	NC	NC
P	NC	NC	Q7	A	A	C	A	A	NC	NC	NC
R	TDO	TCK	A	A	A	C#	A	A	A	TMS	TDI

A	: Address inputs	DLL#	: DLL/PLL disable
D0 to D7	: Data inputs	TMS	: IEEE 1149.1 Test input
Q0 to Q7	: Data outputs	TDI	: IEEE 1149.1 Test input
LD#	: Synchronous load	TCK	: IEEE 1149.1 Clock input
R, W#	: Read Write input	TDO	: IEEE 1149.1 Test output
NW0#, NW1#	: Nibble Write data select	V_{REF}	: HSTL input reference input
K, K#	: Input clock	V_{DD}	: Power Supply
C, C#	: Output clock	$V_{DD}Q$	: Power Supply
CQ, CQ#	: Echo clock	V_{SS}	: Ground
ZQ	: Output impedance matching	NC	: No connection

Remarks 1. ×××# indicates active LOW signal.

2. Refer to **Package Drawing** for the index mark.

3. 2A, 7A and 10A are expansion addresses: 10A for 36Mb, 2A for 72Mb and 7A for 144Mb.
2A and 10A of this product can also be used as NC.

165-pin PLASTIC BGA (13 x 15)

(Top View)

[μPD44164095A-A]

2M x 9-bit

	1	2	3	4	5	6	7	8	9	10	11
A	CQ#	V_{SS}	A	R, W#	NC	K#	NC	LD#	A	V_{SS}	CQ
B	NC	NC	NC	A	NC	K	BW0#	A	NC	NC	Q4
C	NC	NC	NC	V_{SS}	A	A	A	V_{SS}	NC	NC	D4
D	NC	D5	NC	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	NC	NC
E	NC	NC	Q5	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	D3	Q3
F	NC	NC	NC	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	NC
G	NC	D6	Q6	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	NC
H	DLL#	V_{REF}	$V_{DD}Q$	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	$V_{DD}Q$	V_{REF}	ZQ
J	NC	NC	NC	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	Q2	D2
K	NC	NC	NC	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	NC
L	NC	Q7	D7	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	NC	Q1
M	NC	NC	NC	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	NC	D1
N	NC	D8	NC	V_{SS}	A	A	A	V_{SS}	NC	NC	NC
P	NC	NC	Q8	A	A	C	A	A	NC	D0	Q0
R	TDO	TCK	A	A	A	C#	A	A	A	TMS	TDI

A	: Address inputs	DLL#	: DLL/PLL disable
D0 to D8	: Data inputs	TMS	: IEEE 1149.1 Test input
Q0 to Q8	: Data outputs	TDI	: IEEE 1149.1 Test input
LD#	: Synchronous load	TCK	: IEEE 1149.1 Clock input
R, W#	: Read Write input	TDO	: IEEE 1149.1 Test output
BW0#	: Byte Write data select	V_{REF}	: HSTL input reference input
K, K#	: Input clock	V_{DD}	: Power Supply
C, C#	: Output clock	$V_{DD}Q$	: Power Supply
CQ, CQ#	: Echo clock	V_{SS}	: Ground
ZQ	: Output impedance matching	NC	: No connection

Remarks 1. ×××# indicates active LOW signal.

2. Refer to **Package Drawing** for the index mark.

3. 2A, 7A and 10A are expansion addresses: 10A for 36Mb, 2A for 72Mb and 7A for 144Mb.
2A and 10A of this product can also be used as NC.

165-pin PLASTIC BGA (13 x 15)

(Top View)

[μPD44164185A-A]

1M x 18-bit

	1	2	3	4	5	6	7	8	9	10	11
A	CQ#	V_{SS}	NC	R, W#	BW1#	K#	NC	LD#	A	V_{SS}	CQ
B	NC	Q9	D9	A	NC	K	BW0#	A	NC	NC	Q8
C	NC	NC	D10	V_{SS}	A	A	A	V_{SS}	NC	Q7	D8
D	NC	D11	Q10	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	NC	D7
E	NC	NC	Q11	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	D6	Q6
F	NC	Q12	D12	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	Q5
G	NC	D13	Q13	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	NC	D5
H	DLL#	V_{REF}	$V_{DD}Q$	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	$V_{DD}Q$	V_{REF}	ZQ
J	NC	NC	D14	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	Q4	D4
K	NC	NC	Q14	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	NC	D3	Q3
L	NC	Q15	D15	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	NC	NC	Q2
M	NC	NC	D16	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	NC	Q1	D2
N	NC	D17	Q16	V_{SS}	A	A	A	V_{SS}	NC	NC	D1
P	NC	NC	Q17	A	A	C	A	A	NC	D0	Q0
R	TDO	TCK	A	A	A	C#	A	A	A	TMS	TDI

A	: Address inputs	DLL#	: DLL/PLL disable
D0 to D17	: Data inputs	TMS	: IEEE 1149.1 Test input
Q0 to Q17	: Data outputs	TDI	: IEEE 1149.1 Test input
LD#	: Synchronous load	TCK	: IEEE 1149.1 Clock input
R, W#	: Read Write input	TDO	: IEEE 1149.1 Test output
BW0#, BW1#	: Byte Write data select	V_{REF}	: HSTL input reference input
K, K#	: Input clock	V_{DD}	: Power Supply
C, C#	: Output clock	$V_{DD}Q$	: Power Supply
CQ, CQ#	: Echo clock	V_{SS}	: Ground
ZQ	: Output impedance matching	NC	: No connection

Remarks 1. ×××# indicates active LOW signal.

2. Refer to **Package Drawing** for the index mark.

3. 2A, 3A and 10A are expansion addresses: 3A for 36Mb, 10A for 72Mb and 2A for 144Mb.
2A and 10A of this product can also be used as NC.

165-pin PLASTIC BGA (13 x 15)

(Top View)

[μPD44164365A-A]

512K x 36-bit

	1	2	3	4	5	6	7	8	9	10	11
A	CQ#	V_{SS}	NC	R, W#	BW2#	K#	BW1#	LD#	NC	V_{SS}	CQ
B	Q27	Q18	D18	A	BW3#	K	BW0#	A	D17	Q17	Q8
C	D27	Q28	D19	V_{SS}	A	A	A	V_{SS}	D16	Q7	D8
D	D28	D20	Q19	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	Q16	D15	D7
E	Q29	D29	Q20	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	Q15	D6	Q6
F	Q30	Q21	D21	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	D14	Q14	Q5
G	D30	D22	Q22	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	Q13	D13	D5
H	DLL#	V_{REF}	$V_{DD}Q$	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	$V_{DD}Q$	V_{REF}	ZQ
J	D31	Q31	D23	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	D12	Q4	D4
K	Q32	D32	Q23	$V_{DD}Q$	V_{DD}	V_{SS}	V_{DD}	$V_{DD}Q$	Q12	D3	Q3
L	Q33	Q24	D24	$V_{DD}Q$	V_{SS}	V_{SS}	V_{SS}	$V_{DD}Q$	D11	Q11	Q2
M	D33	Q34	D25	V_{SS}	V_{SS}	V_{SS}	V_{SS}	V_{SS}	D10	Q1	D2
N	D34	D26	Q25	V_{SS}	A	A	A	V_{SS}	Q10	D9	D1
P	Q35	D35	Q26	A	A	C	A	A	Q9	D0	Q0
R	TDO	TCK	A	A	A	C#	A	A	A	TMS	TDI

A	: Address inputs	DLL#	: DLL/PLL disable
D0 to D35	: Data inputs	TMS	: IEEE 1149.1 Test input
Q0 to Q35	: Data outputs	TDI	: IEEE 1149.1 Test input
LD#	: Synchronous load	TCK	: IEEE 1149.1 Clock input
R, W#	: Read Write input	TDO	: IEEE 1149.1 Test output
BW0# to BW3#	: Byte Write data select	V_{REF}	: HSTL input reference input
K, K#	: Input clock	V_{DD}	: Power Supply
C, C#	: Output clock	$V_{DD}Q$	: Power Supply
CQ, CQ#	: Echo clock	V_{SS}	: Ground
ZQ	: Output impedance matching	NC	: No connection

Remarks 1. ×××# indicates active LOW signal.

2. Refer to **Package Drawing** for the index mark.

3. 3A, 9A and 10A are expansion addresses: 9A for 36Mb, 3A for 72Mb and 10A for 144Mb.
2A and 10A of this product can also be used as NC.

Pin Identification **(1/2)**

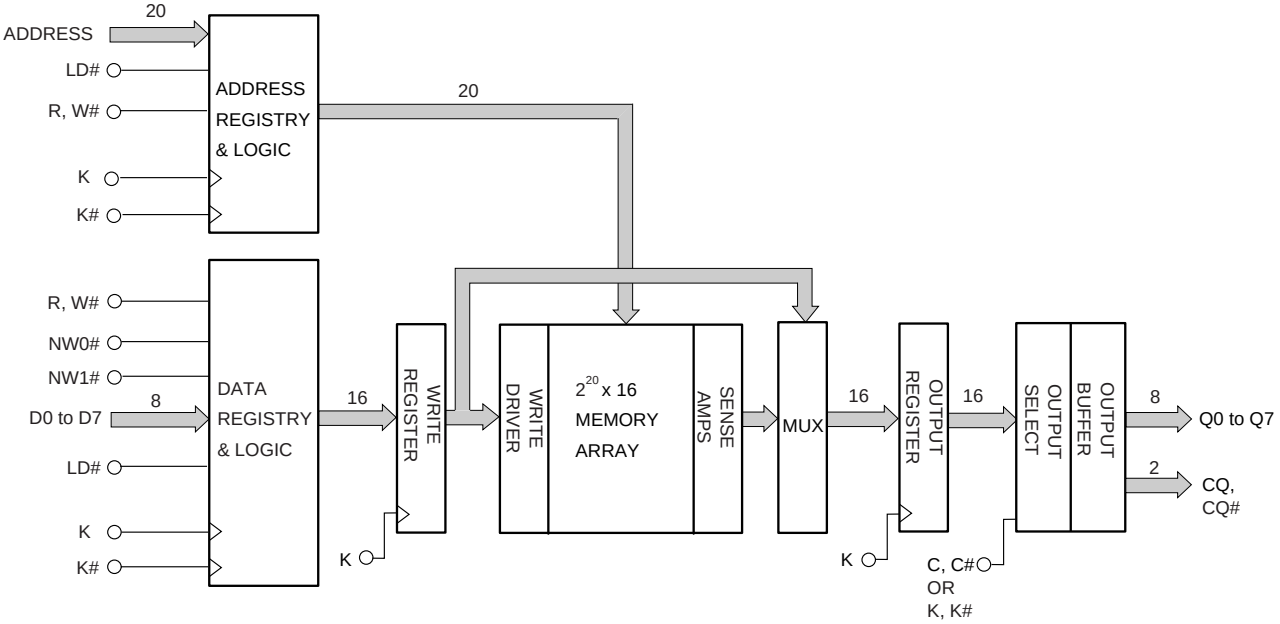
Symbol	Description
A	Synchronous Address Inputs: These inputs are registered and must meet the setup and hold times around the rising edge of K. All transactions operate on a burst of two words (one clock period of bus activity). These inputs are ignored when device is deselected, i.e., NOP (LD# = HIGH).
D0 to Dxx	Synchronous Data Inputs: Input data must meet setup and hold times around the rising edges of K and K# during WRITE operations. See **Pin Configurations** for ball site location of individual signals. x8 device uses D0 to D7. x9 device uses D0 to D8. x18 device uses D0 to D17. x36 device uses D0 to D35.
Q0 to Qxx	Synchronous Data Outputs: Output data is synchronized to the respective C and C# or to K and K# rising edges if C and C# are tied HIGH. Data is output in synchronization with C and C# (or K and K#), depending on the LD# and R, W# command. See **Pin Configurations** for ball site location of individual signals. x8 device uses Q0 to Q7. x9 device uses Q0 to Q8. x18 device uses Q0 to Q17. x36 device uses Q0 to Q35.
LD#	Synchronous Load: This input is brought LOW when a bus cycle sequence is to be defined. This definition includes address and read/write direction. All transactions operate on a burst of 2 data (one clock period of bus activity).
R, W#	Synchronous Read/Write Input: When LD# is LOW, this input designates the access type (READ when R, W# is HIGH, WRITE when R, W# is LOW) for the loaded address. R, W# must meet the setup and hold times around the rising edge of K.
BWx# NWx#	Synchronous Byte Writes (Nibble Writes on x8): When LOW these inputs cause their respective byte or nibble to be registered and written during WRITE cycles. These signals must meet setup and hold times around the rising edges of K and K# for each of the two rising edges comprising the WRITE cycle. See **Pin Configurations** for signal to data relationships. x8 device uses NW0#, NW1#. x9 device uses BW0#. x18 device uses BW0#, BW1#. x36 device uses BW0# to BW3#. See **Byte Write Operation** for relation between BWx#, NWx# and Dxx.
K, K#	Input Clock: This input clock pair registers address and control inputs on the rising edge of K, and registers data on the rising edge of K and the rising edge of K#. K# is ideally 180 degrees out of phase with K. All synchronous inputs must meet setup and hold times around the clock rising edges.
C, C#	Output Clock: This clock pair provides a user controlled means of tuning device output data. The rising edge of C# is used as the output timing reference for first output data. The rising edge of C is used as the output reference for second output data. Ideally, #C is 180 degrees out of phase with C. When use of K and K# as the reference instead of C and C#, then fixed C and C# to HIGH. Operation cannot be guaranteed unless C and C# are fixed to HIGH (i.e. toggle of C and C#)

(2/2)

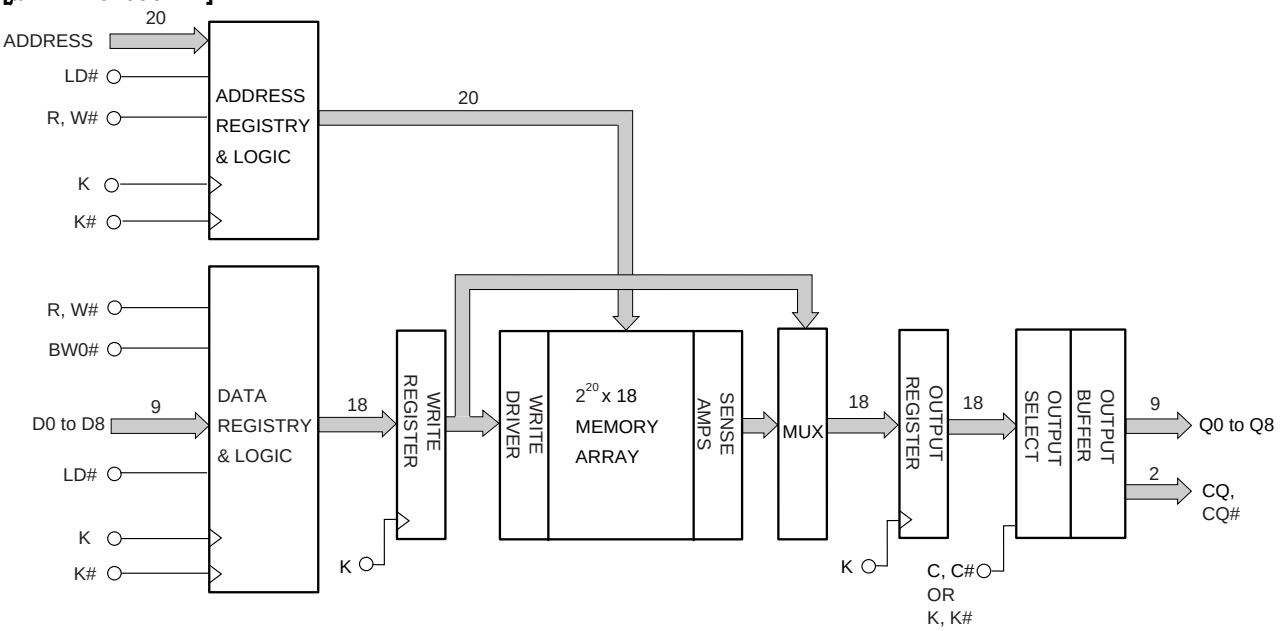
Symbol	Description
CQ, CQ#	Synchronous Echo Clock Outputs. The rising edges of these outputs are tightly matched to the synchronous data outputs and can be used as a data valid indication. These signals run freely and do not stop when Q tristates. If C and C# are stopped (if K and K# are stopped in the single clock mode), CQ and CQ# will also stop.
ZQ	Output Impedance Matching Input: This input is used to tune the device outputs to the system data bus impedance. Q, CQ and CQ# output impedance are set to 0.2 x RQ, where RQ is a resistor from this bump to ground. The output impedance can be minimized by directly connect ZQ to $V_{DD}Q$. This pin cannot be connected directly to GND or left unconnected. The output impedance is adjusted every 1,024 cycles upon power-up to account for drifts in supply voltage and temperature. After replacement for a resistor, the new output impedance is reset by implementing power-on sequence.
DLL#	DLL/PLL Disable: When debugging the system or board, the operation can be performed at a clock frequency slower than TKHKH (MAX.) without the DLL circuit being used, if DLL# = LOW. The AC/DC characteristics cannot be guaranteed. For normal operation, DLL# must be HIGH and it can be connected to $V_{DD}Q$ through a 10 kΩ or less resistor.
TMS TDI	IEEE 1149.1 Test Inputs: 1.8 V I/O level. These balls may be left Not Connected if the JTAG function is not used in the circuit.
TCK	IEEE 1149.1 Clock Input: 1.8 V I/O level. This pin must be tied to V_{SS} if the JTAG function is not used in the circuit.
TDO	IEEE 1149.1 Test Output: 1.8 V I/O level.
V_{REF}	HSTL Input Reference Voltage: Nominally $V_{DD}Q/2$. Provides a reference voltage for the input buffers.
V_{DD}	Power Supply: 1.8 V nominal. See **Recommended DC Operating Conditions** and **DC Characteristics** for range.
$V_{DD}Q$	Power Supply: Isolated Output Buffer Supply. Nominally 1.5 V. 1.8 V is also permissible. See **Recommended DC Operating Conditions** and **DC Characteristics** for range.
V_{SS}	Power Supply: Ground
NC	No Connect: These signals are not connected internally.

Block Diagram

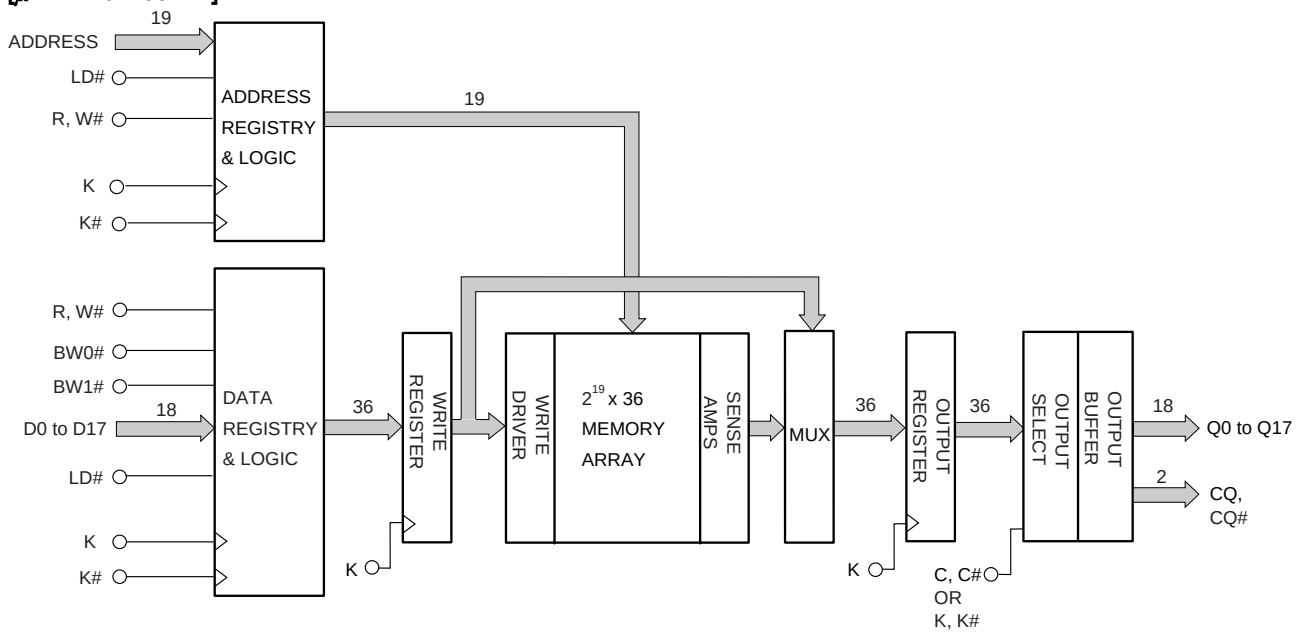
[μPD44164085A-A]



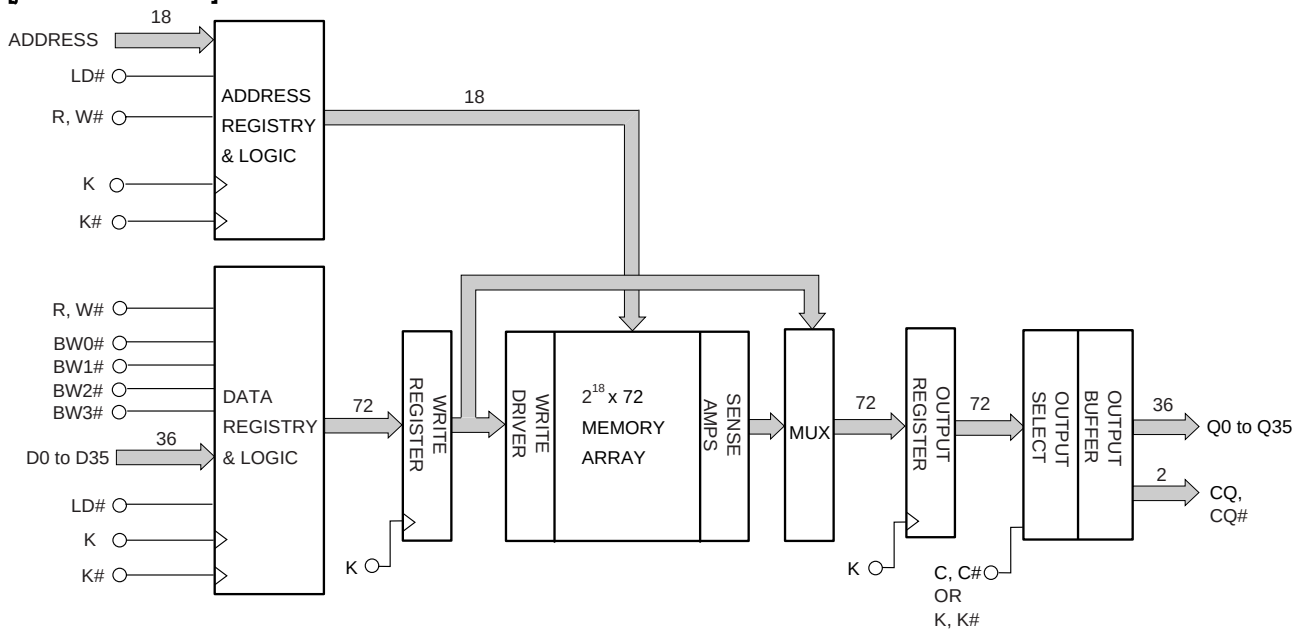
[μPD44164095A-A]



[μPD44164185A-A]



[μPD44164365A-A]



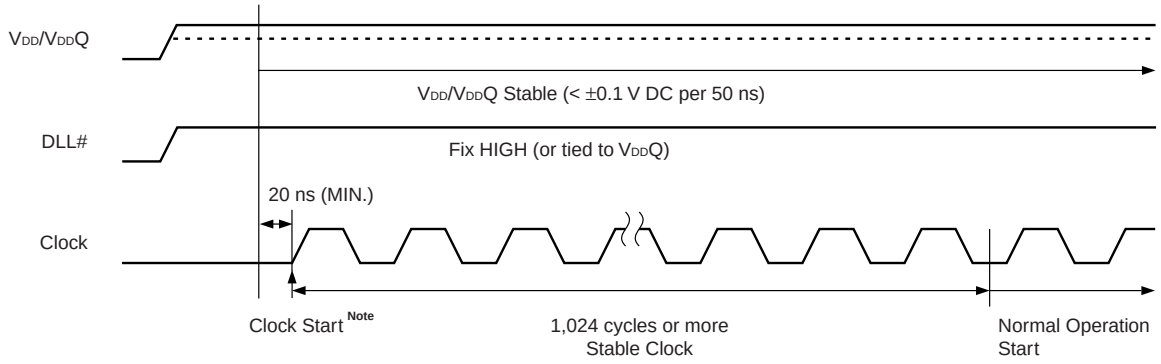
Power-on Sequence

The following two timing charts show the recommended power-on sequence, i.e., when starting the clock after $V_{DD}/V_{DD}Q$ stable and when starting the clock before $V_{DD}/V_{DD}Q$ stable.

1. Clock starts after $V_{DD}/V_{DD}Q$ stable

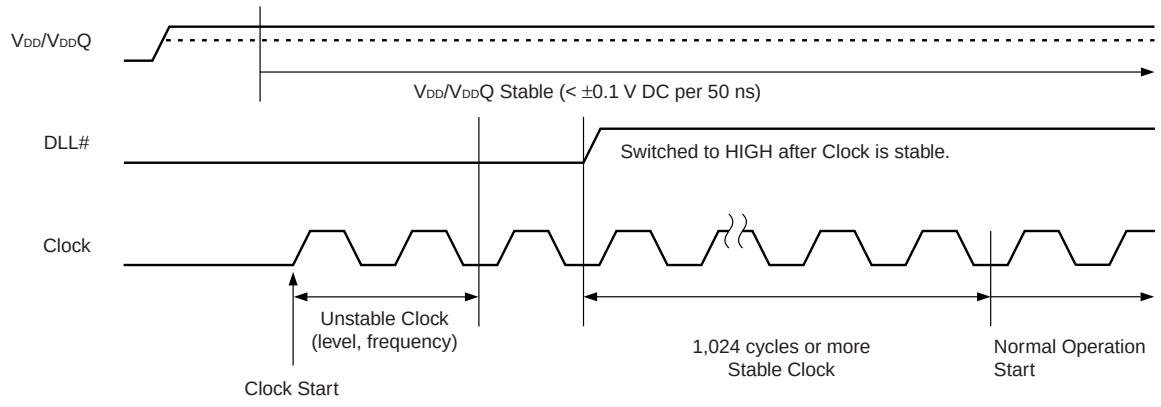
The clock is supplied from a controller.

(a)

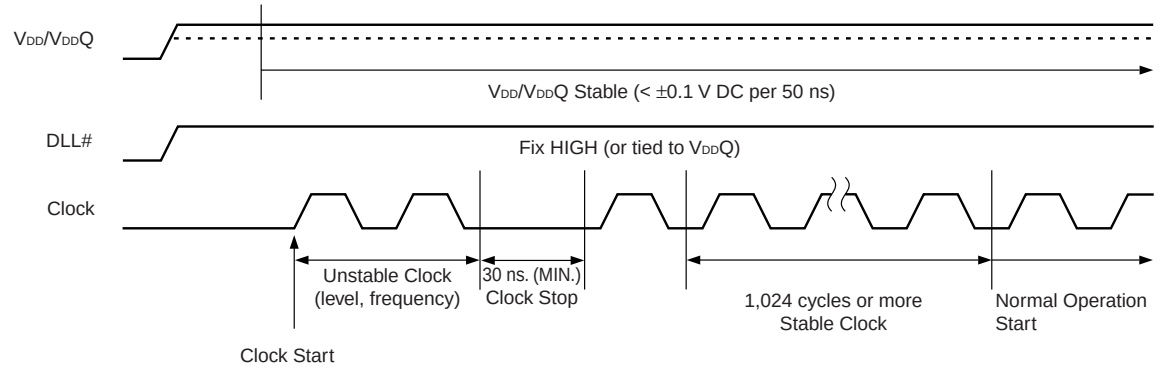


Note Input a stable clock from the start.

(b)



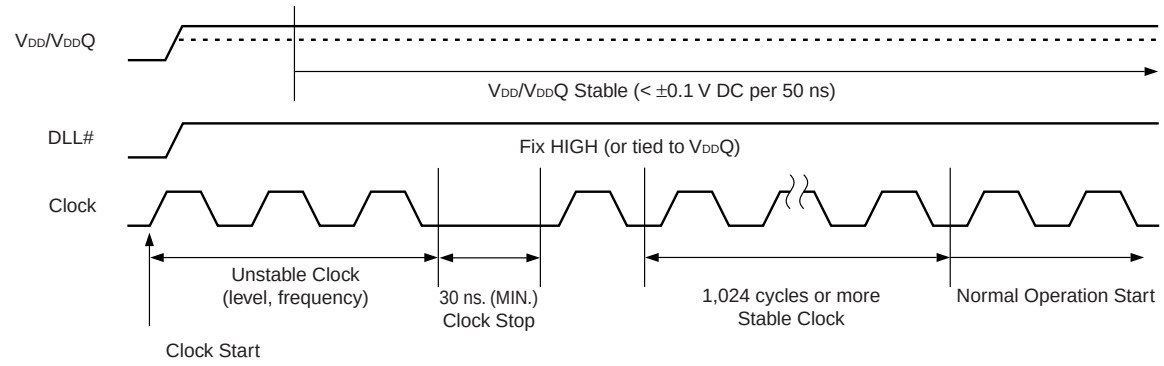
(c)



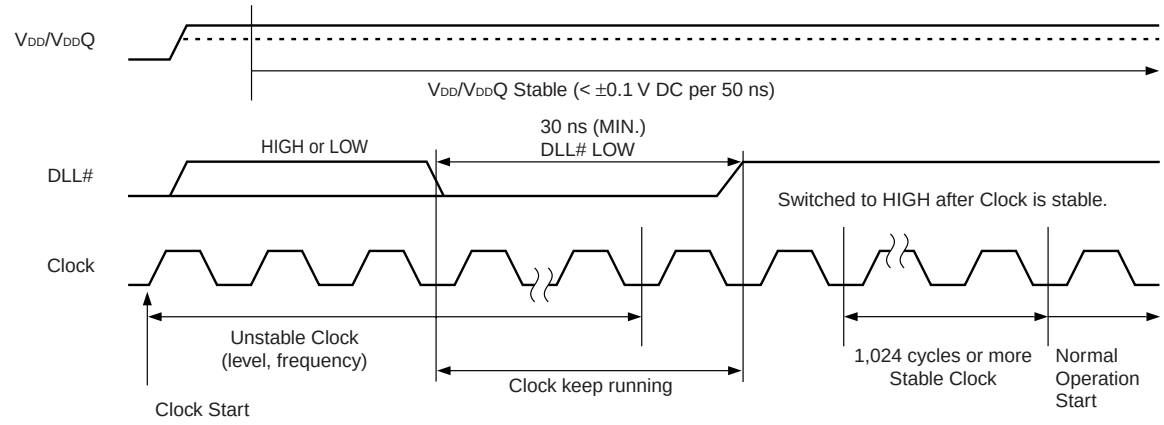
2. Clock starts before V_{DD}/V_{DD}Q stable

The clock is supplied from a clock generator.

(a)



(b)



Truth Table

Operation	LD#	R, W#	CLK	D or Q			
WRITE cycle	L	L	L → H	Data in			
Load address, input write data on two consecutive K and K# rising edge					Input data	D(A+0)	D(A+1)
					Input clock	K(t+1) ↑	K#(t+1) ↑
READ cycle	L	H	L → H	Data out			
Load address, read data on two consecutive C and C# rising edge					Output data	Q(A+0)	Q(A+1)
					Output clock	C#(t+1) ↑	C(t+2) ↑
NOP (No operation)	H	X	L → H	D = X, Q = High-Z			
Clock stop	X	X	Stopped	Previous state			

Remarks 1. H : HIGH, L : LOW, × : don't care, ↑ : rising edge.

2. Data inputs are registered at K and K# rising edges. Data outputs are delivered at C and C# rising edges except if C and C# are HIGH then Data outputs are delivered at K and K# rising edges.

3. All control inputs in the truth table must meet setup/hold times around the rising edge (LOW to HIGH) of K. All control inputs are registered during the rising edge of K.

4. This device contains circuitry that ensure the outputs to be in high impedance during power-up.

5. Refer to state diagram and timing diagrams for clarification.

6. It is recommended that K = K# = C = C# when clock is stopped. This is not essential but permits most rapid restart by overcoming transmission line charging symmetrically.

Byte Write Operation

[μPD44164085A-A]

Operation	K	K#	NW0#	NW1#
Write D0 to D7	L → H	–	0	0
	–	L → H	0	0
Write D0 to D3	L → H	–	0	1
	–	L → H	0	1
Write D4 to D7	L → H	–	1	0
	–	L → H	1	0
Write nothing	L → H	–	1	1
	–	L → H	1	1

Remarks 1. H : HIGH, L : LOW, → : rising edge.

2. Assumes a WRITE cycle was initiated. NW0# and NW1# can be altered for any portion of the BURST WRITE operation provided that the setup and hold requirements are satisfied.

[μPD44164095A-A]

Operation	K	K#	BW0#
Write D0 to D8	L → H	–	0
	–	L → H	0
Write nothing	L → H	–	1
	–	L → H	1

Remarks 1. H : HIGH, L : LOW, → : rising edge.

2. Assumes a WRITE cycle was initiated. BW0# can be altered for any portion of the BURST WRITE operation provided that the setup and hold requirements are satisfied.

[μPD44164185A-A]

Operation	K	K#	BW0#	BW1#
Write D0 to D17	L → H	–	0	0
	–	L → H	0	0
Write D0 to D8	L → H	–	0	1
	–	L → H	0	1
Write D9 to D17	L → H	–	1	0
	–	L → H	1	0
Write nothing	L → H	–	1	1
	–	L → H	1	1

Remarks 1. H : HIGH, L : LOW, → : rising edge.

2. Assumes a WRITE cycle was initiated. BW0# and BW1# can be altered for any portion of the BURST WRITE operation provided that the setup and hold requirements are satisfied.

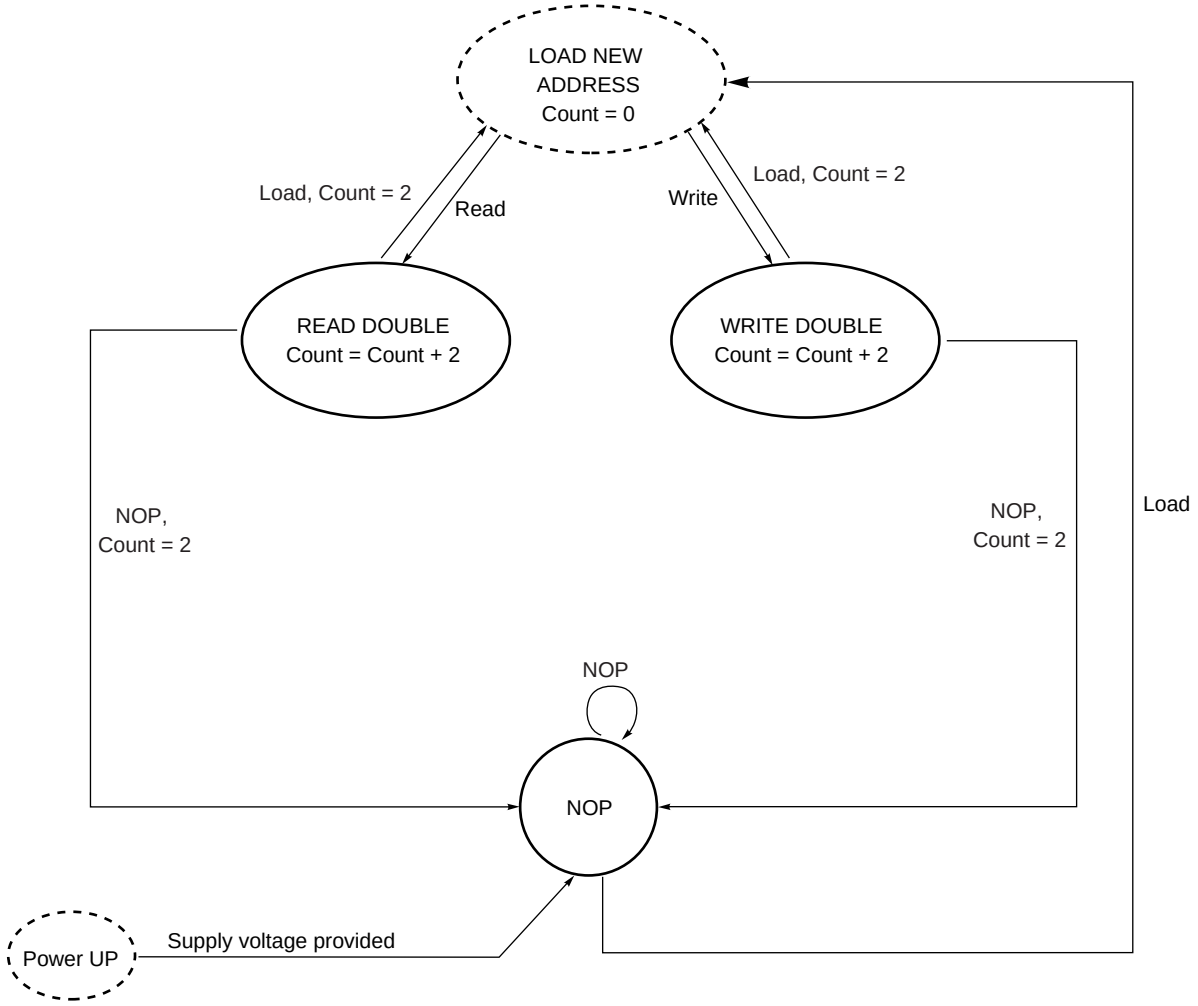
[μPD44164365A-A]

Operation	K	K#	BW0#	BW1#	BW2#	BW3#
Write D0 to D35	L → H	–	0	0	0	0
	–	L → H	0	0	0	0
Write D0 to D8	L → H	–	0	1	1	1
	–	L → H	0	1	1	1
Write D9 to D17	L → H	–	1	0	1	1
	–	L → H	1	0	1	1
Write D18 to D26	L → H	–	1	1	0	1
	–	L → H	1	1	0	1
Write D27 to D35	L → H	–	1	1	1	0
	–	L → H	1	1	1	0
Write nothing	L → H	–	1	1	1	1
	–	L → H	1	1	1	1

Remarks 1. H : HIGH, L : LOW, → : rising edge.

2. Assumes a WRITE cycle was initiated. BW0# to BW3# can be altered for any portion of the BURST WRITE operation provided that the setup and hold requirements are satisfied.

Bus Cycle State Diagram



Remark State machine control timing sequence is controlled by K.

Electrical Specifications

Absolute Maximum Ratings

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Supply voltage	V_{DD}		–0.5		+2.5	V
Output supply voltage	V_{DDQ}		–0.5		V_{DD}	V
Input voltage	V_{IN}		–0.5		V_{DD} + 0.5 (2.5 V MAX.)	V
Input / Output voltage	$V_{I/O}$		–0.5		V_{DDQ} + 0.5 (2.5 V MAX.)	V
Operating ambient temperature	T_A	Commercial	0		+70	°C
		Industrial	–40		+85	
Storage temperature	T_{stg}		–55		+125	°C

Caution Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended DC Operating Conditions

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	Note
Supply voltage	V_{DD}		1.7		1.9	V	
Output supply voltage	V_{DDQ}		1.4		V_{DD}	V	1
Input HIGH voltage	$V_{IH (DC)}$		V_{REF} + 0.1		V_{DDQ} + 0.3	V	1, 2
Input LOW voltage	$V_{IL (DC)}$		–0.3		V_{REF} – 0.1	V	1, 2
Clock input voltage	V_{IN}		–0.3		V_{DDQ} + 0.3	V	1, 2
Reference voltage	V_{REF}		0.68		0.95	V	

Notes 1. During normal operation, V_{DDQ} must not exceed V_{DD}.

2. Power-up: $V_{IH} \leq V_{DDQ} + 0.3$ V and $V_{DD} \leq 1.7$ V and $V_{DDQ} \leq 1.4$ V for $t \leq 200$ ms

Recommended AC Operating Conditions

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	Note
Input HIGH voltage	$V_{IH (AC)}$		V_{REF} + 0.2		–	V	1
Input LOW voltage	$V_{IL (AC)}$		–		V_{REF} – 0.2	V	1

Note 1. Overshoot: $V_{IH (AC)} \leq V_{DD} + 0.7$ V (2.5 V MAX.) for $t \leq TKHKH/2$

Undershoot: $V_{IL (AC)} \geq -0.5$ V for $t \leq TKHKH/2$

Control input signals may not have pulse widths less than TKHKL (MIN.) or operate at cycle rates less than TKHKH (MIN.).

DC Characteristics (V_{DD} = 1.8 ± 0.1 V)

Parameter	Symbol	Test condition			MIN.	TYP.	MAX.			Unit	Note
							x8, x9	x18	x36		
Input leakage current	I_{LI}				–2	–	+2			μA	
I/O leakage current	I_{LO}				–2	–	+2			μA	
Operating supply current (Read cycle/ Write cycle)	I_{DD}	Note1	Commercial (T_A = 0 to +70°C)	-E33			520	570	660	mA	
				-E37			–	520	–		
				-E40			450	490	570		
				-E50			390	420	490		
			Industrial (T_A = –40 to +85°C)	-E37Y			500	540	–		
				-E40Y			470	510	–		
				-E50Y			410	430	–		
Standby supply current (NOP)	I_{SB1}	Note1	Commercial (T_A = 0 to +70°C)	-E33			300	300	300	mA	
				-E37			–	290	–		
				-E40			280	280	280		
				-E50			260	260	260		
			Industrial (T_A = –40 to +85°C)	-E37Y			310	310	–		
				-E40Y			300	300	–		
				-E50Y			280	280	–		
Output HIGH voltage	$V_{OH(Low)}$	$\|I_{OH}\| \le 0.1$ mA			V_{DDQ} – 0.2	–	V_{DDQ}			V	4, 5
	V_{OH}	Note2			V_{DDQ}/2–0.12	–	V_{DDQ}/2+0.12			V	4, 5
Output LOW voltage	$V_{OL(Low)}$	$I_{OL} \le 0.1$ mA			V_{SS}	–	0.2			V	4, 5
	V_{OL}	Note3			V_{DDQ}/2–0.12	–	V_{DDQ}/2+0.12			V	4, 5

Notes 1. $V_{IN} \le V_{IL}$ or $V_{IN} \ge V_{IH}$, $I_{I/O}$ = 0 mA, Cycle = MAX.

2. Outputs are impedance-controlled. $|I_{OH}| = (V_{DDQ}/2)/(RQ/5) \pm 15$ % for values of 175 Ω ≤ RQ ≤ 350 Ω.

3. Outputs are impedance-controlled. $I_{OL} = (V_{DDQ}/2)/(RQ/5) \pm 15$ for values of 175 Ω ≤ RQ ≤ 350 Ω.

4. AC load current is higher than the shown DC values.

5. HSTL outputs meet JEDEC HSTL Class I standards.

Capacitance (T_A = 25°C, f = 1 MHz)

Parameter	Symbol	Test conditions	MIN.	TYP.	MAX.	Unit
Input capacitance (Address, Control)	C_{IN}	V_{IN} = 0 V		4	5	pF
Input / Output capacitance (D, Q, CQ, CQ#)	$C_{I/O}$	$V_{I/O}$ = 0 V		6	7	pF
Clock Input capacitance	C_{clk}	V_{clk} = 0 V		5	6	pF

Remark These parameters are periodically sampled and not 100% tested.

Thermal Resistance

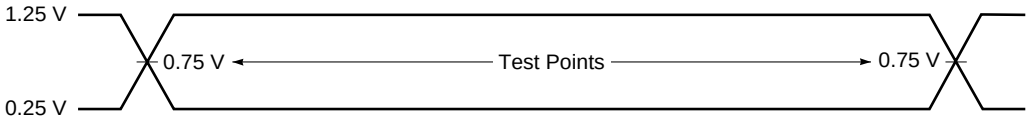
Parameter	Symbol	Test conditions	MIN.	TYP.	MAX.	Unit
Thermal resistance (junction – ambient)	$\theta_{j\text{-}a}$			25.1		°C/W
Thermal resistance (junction – case)	$\theta_{j\text{-}c}$			2.8		°C/W

Remark These parameters are simulated under the condition of air flow velocity = 1 m/s.

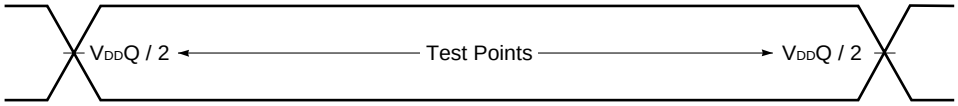
AC Characteristics (V_{DD} = 1.8 ± 0.1 V)

AC Test Conditions (V_{DD} = 1.8 ± 0.1 V, $V_{DD}Q$ = 1.4 V to V_{DD})

Input waveform (Rise / Fall time ≤ 0.3 ns)

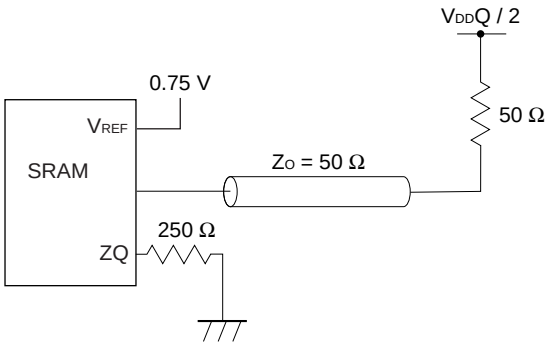


Output waveform



Output load condition

Figure 1. External load at test



Read and Write Cycle

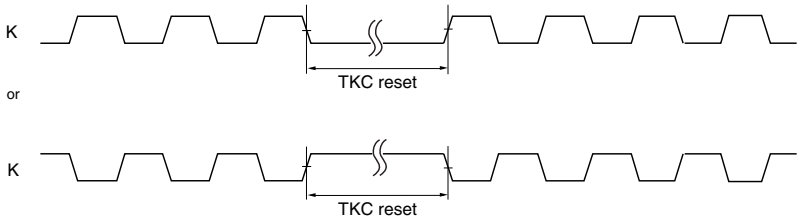
Parameter		Symbol	-E33 (300 MHz)		-E37, -E37Y (270 MHz)		-E40, -E40Y (250 MHz)		-E50, -E50Y (200 MHz)		Unit	Note
			MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Clock												
Average Clock cycle time (K, K#, C, C#)		TKHKH	3.3	8.4	3.7	8.4	4.0	8.4	5.0	8.4	ns	1
Clock phase jitter (K, K#, C, C#)		TKC var	–	0.2	–	0.2	–	0.2	–	0.2	ns	2
Clock HIGH time (K, K#, C, C#)		TKHKL	1.32	–	1.5	–	1.6	–	2.0	–	ns	
Clock LOW time (K, K#, C, C#)		TKLKH	1.32	–	1.5	–	1.6	–	2.0	–	ns	
Clock HIGH to Clock# HIGH (K→K#, C→C#)		TKHK#H	1.49	–	1.7	–	1.8	–	2.2	–	ns	
Clock# HIGH to Clock HIGH (K#→K, C#→C)		TK#HKH	1.49	–	1.7	–	1.8	–	2.2	–	ns	
Clock to data clock (K→C, K#→C#)	270 to 300 MHz	TKHCH	0	1.45	–	–	–	–	–	–	ns	
	250 to 270 MHz		0	1.65	0	1.65	–	–	–	–		
	200 to 250 MHz		0	1.8	0	1.8	0	1.8	–	–		
	167 to 200 MHz		0	2.3	0	2.3	0	2.3	0	2.3		
	133 to 167 MHz		0	2.8	0	2.8	0	2.8	0	2.8		
	< 133 MHz		0	3.55	0	3.55	0	3.55	0	3.55		
DLL/PLL lock time (K, C)		TKC lock	1,024	–	1,024	–	1,024	–	1,024	–	Cycle	3
K static to DLL/PLL reset		TKC reset	30	–	30	–	30	–	30	–	ns	4
Output Times												
C, C# HIGH to output valid		TCHQV	–	0.45	–	0.45	–	0.45	–	0.45	ns	
C, C# HIGH to output hold		TCHQX	– 0.45	–	–0.45	–	– 0.45	–	– 0.45	–	ns	
C, C# HIGH to echo clock valid		TCHCQV	–	0.45	–	0.45	–	0.45	–	0.45	ns	
C, C# HIGH to echo clock hold		TCHCQX	– 0.45	–	–0.45	–	– 0.45	–	– 0.45	–	ns	
CQ, CQ# HIGH to output valid		TCQHQV	–	0.27	–	0.3	–	0.3	–	0.35	ns	5
CQ, CQ# HIGH to output hold		TCQHQX	– 0.27	–	–0.3	–	– 0.3	–	– 0.35	–	ns	5
C HIGH to output High-Z		TCHQZ	–	0.45	–	0.45	–	0.45	–	0.45	ns	
C HIGH to output Low-Z		TCHQX1	– 0.45	–	–0.45	–	– 0.45	–	– 0.45	–	ns	
Setup Times												
Address valid to K rising edge		TAVKH	0.4	–	0.5	–	0.5	–	0.6	–	ns	6
Synchronous load input (LD#), read write input (R, W#) valid to K rising edge		TIVKH	0.4	–	0.5	–	0.5	–	0.6	–	ns	6
Data inputs and write data select inputs (BWx#, NWx#) valid to K, K# rising edge		TDVKH	0.3	–	0.35	–	0.35	–	0.4	–	ns	6
Hold Times												
K rising edge to address hold		TKHAX	0.4	–	0.5	–	0.5	–	0.6	–	ns	6
K rising edge to synchronous load input (LD#), read write input (R, W#) hold		TKHIX	0.4	–	0.5	–	0.5	–	0.6	–	ns	6
K, K# rising edge to data inputs and write data select inputs (BWx#, NWx#) hold		TKHDX	0.3	–	0.35	–	0.35	–	0.4	–	ns	6

Notes 1. When debugging the system or board, these products can operate at a clock frequency slower than TKHKH (MAX.) without the DLL/PLL circuit being used, if DLL# = LOW. Read latency (RL) is changed to 1.5 clock in this operation. The AC/DC characteristics cannot be guaranteed, however.

2. Clock phase jitter is the variance from clock rising edge to the next expected clock rising edge. TKC var (MAX.) indicates a peak-to-peak value.

3. V_{DD} slew rate must be less than 0.1 V DC per 50 ns for DLL/PLL lock retention.
DLL/PLL lock time begins once V_{DD} and input clock are stable.
It is recommended that the device is kept NOP (LD# = HIGH) during these cycles.

4. K input is monitored for this operation. See below for the timing.



5. Echo clock is very tightly controlled to data valid / data hold. By design, there is a ± 0.1 ns variation from echo clock to data. The data sheet parameters reflect tester guardbands and test setup variations.

6. This is a synchronous device. All addresses, data and control lines must meet the specified setup and hold times for all latching clock edges.

Remarks 1. This parameter is sampled.

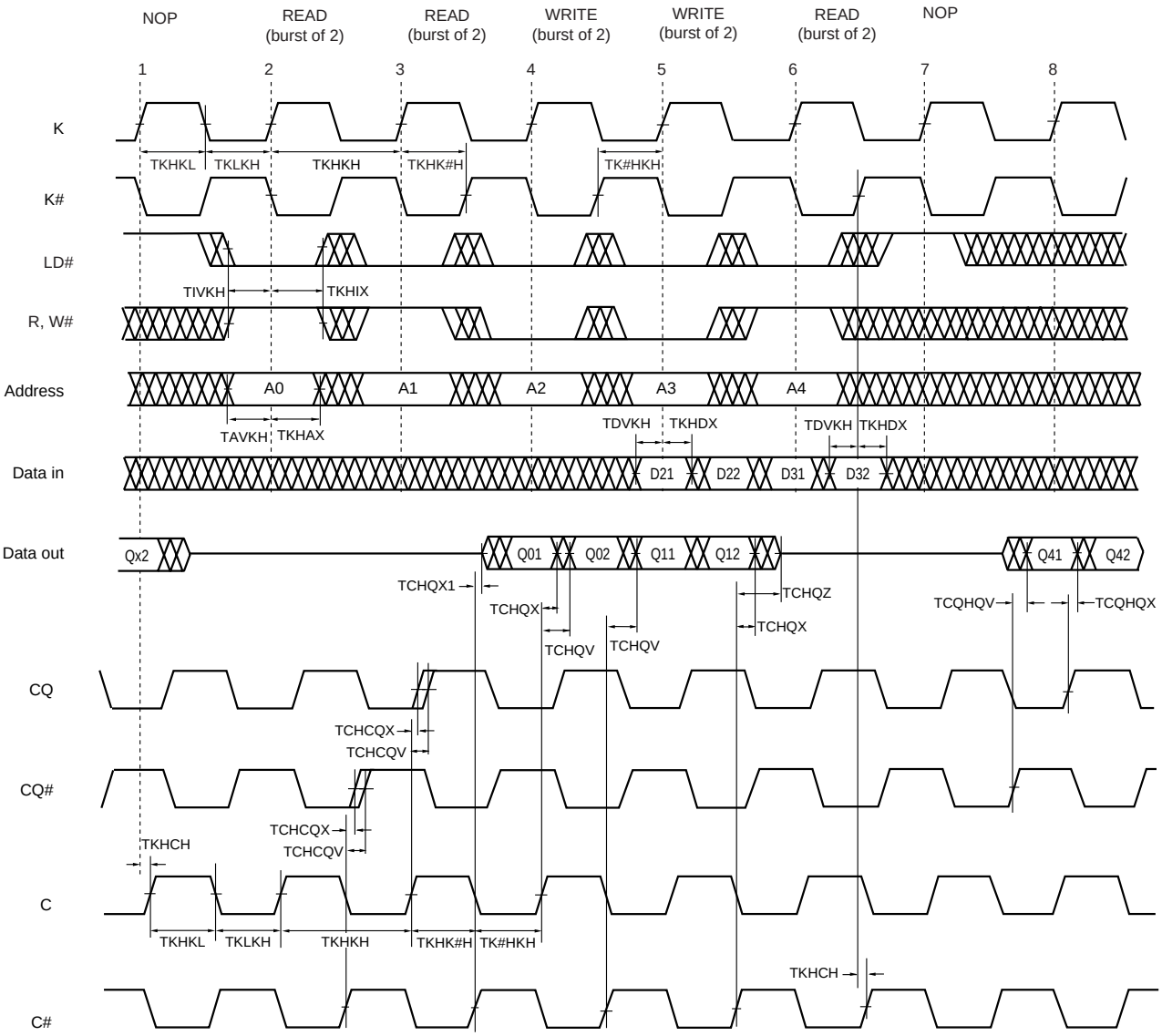
2. Test conditions as specified with the output loading as shown in AC Test Conditions unless otherwise noted.

3. Control input signals may not be operated with pulse widths less than TKHKL (MIN.).

4. If C, C# are tied HIGH, K, K# become the references for C, C# timing parameters.

5. $V_{DD}Q$ is 1.5 V DC.

Read and Write Timing

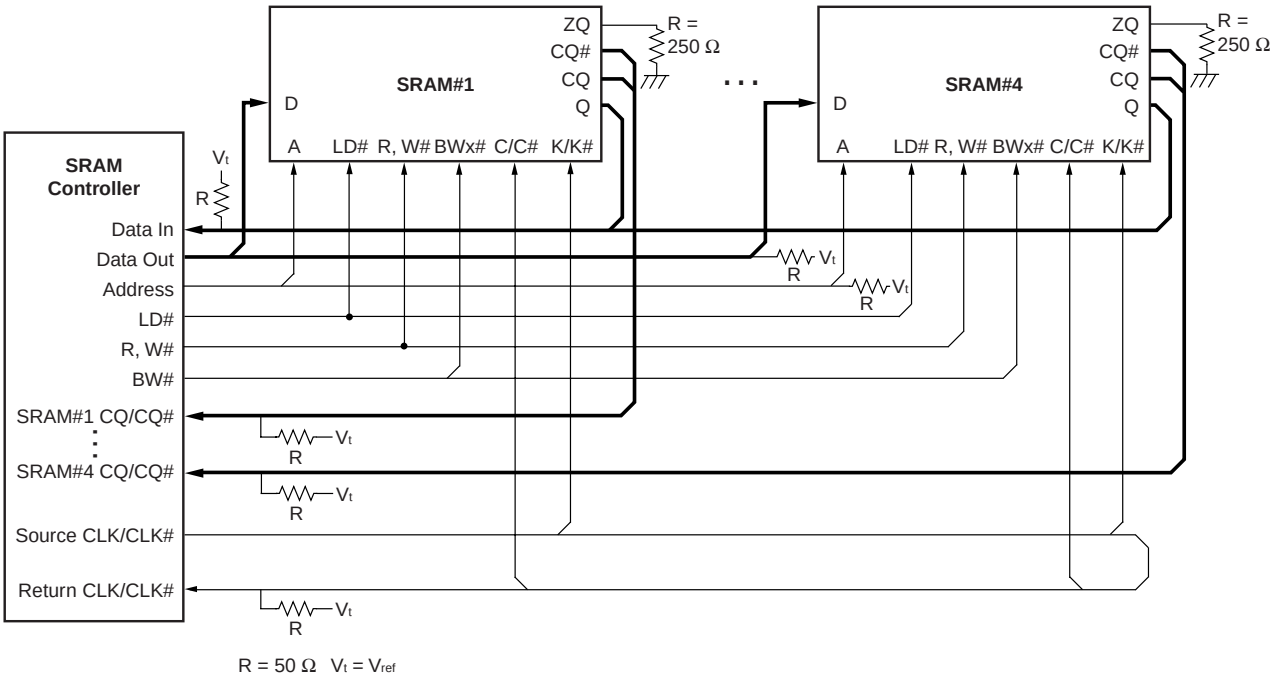


Remarks 1. Q01 refers to output from address A0+0.
Q02 refers to output from the next internal burst address following A0, i.e., A0+1.

2. Outputs are disabled (high impedance) 2.5 clocks after the last READ (LD# = LOW, R, W# = HIGH) is input in the sequences of [READ]-[NOP] and [READ]-[WRITE].

3. In this example, if address A4 = A3, data Q41 = D31 and Q42 = D32.
Write data is forwarded immediately as read results.

Application Example



Remark AC specifications are defined at the condition of SRAM outputs, CQ, CQ# and Q with termination.

JTAG Specification

These products support a limited set of JTAG functions as in IEEE standard 1149.1.

Test Access Port (TAP) Pins

Pin name	Pin assignments	Description
TCK	2R	Test Clock Input. All input are captured on the rising edge of TCK and all outputs propagate from the falling edge of TCK.
TMS	10R	Test Mode Select. This is the command input for the TAP controller state machine.
TDI	11R	Test Data Input. This is the input side of the serial registers placed between TDI and TDO. The register placed between TDI and TDO is determined by the state of the TAP controller state machine and the instruction that is currently loaded in the TAP instruction.
TDO	1R	Test Data Output. This is the output side of the serial registers placed between TDI and TDO. Output changes in response to the falling edge of TCK.

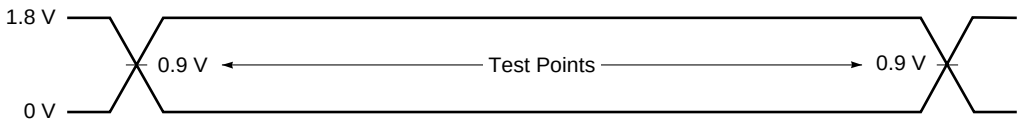
Remark The device does not have TRST (TAP reset). The Test-Logic Reset state is entered while TMS is held HIGH for five rising edges of TCK. The TAP controller state is also reset on the SRAM POWER-UP.

JTAG DC Characteristics (V_{DD} = 1.8 ± 0.1 V, unless otherwise noted)

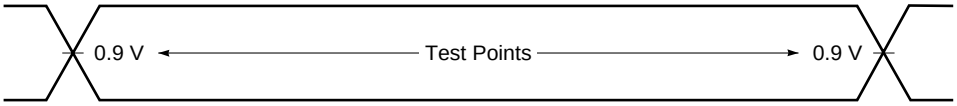
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
JTAG Input leakage current	I_{LI}	0 V ≤ V_{IN} ≤ V_{DD}	–5.0	–	+5.0	μA
JTAG I/O leakage current	I_{LO}	0 V ≤ V_{IN} ≤ V_{DD}Q, Outputs disabled	–5.0	–	+5.0	μA
JTAG input HIGH voltage	V_{IH}		1.3	–	V_{DD}+0.3	V
JTAG input LOW voltage	V_{IL}		–0.3	–	+0.5	V
JTAG output HIGH voltage	V_{OH1}	| I_{OHC} | = 100 μA	1.6	–	–	V
	V_{OH2}	| I_{OHT} | = 2 mA	1.4	–	–	V
JTAG output LOW voltage	V_{OL1}	I_{OLC} = 100 μA	–	–	0.2	V
	V_{OL2}	I_{OLT} = 2 mA	–	–	0.4	V

JTAG AC Test Conditions

Input waveform (Rise / Fall time ≤ 1 ns)

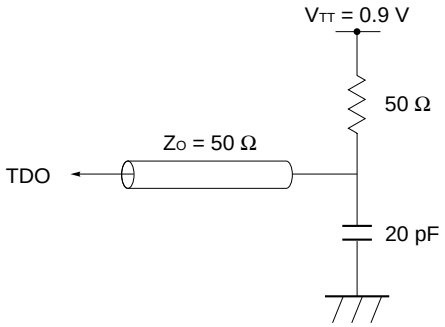


Output waveform



Output load

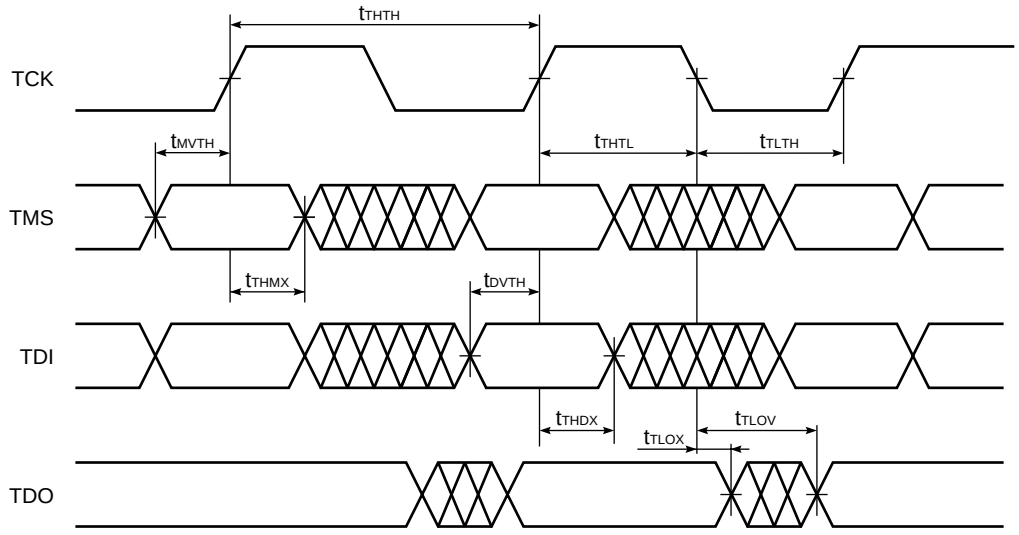
Figure 2. External load at test



JTAG AC Characteristics

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Clock						
Clock cycle time	t_{THTH}		50	–	–	ns
Clock frequency	f_{TF}		–	–	20	MHz
Clock HIGH time	t_{THTL}		20	–	–	ns
Clock LOW time	t_{TLTH}		20	–	–	ns
Output time						
TCK LOW to TDO unknown	t_{TLOX}		0	–	–	ns
TCK LOW to TDO valid	t_{TLOV}		–	–	10	ns
Setup time						
TMS setup time	t_{MVTH}		5	–	–	ns
TDI valid to TCK HIGH	t_{DVTH}		5	–	–	ns
Capture setup time	t_{CS}		5	–	–	ns
Hold time						
TMS hold time	t_{THMX}		5	–	–	ns
TCK HIGH to TDI invalid	t_{THDX}		5	–	–	ns
Capture hold time	t_{CH}		5	–	–	ns

JTAG Timing Diagram



Scan Register Definition (1)

Register name	Description
Instruction register	The instruction register holds the instructions that are executed by the TAP controller when it is moved into the run-test/idle or the various data register state. The register can be loaded when it is placed between the TDI and TDO pins. The instruction register is automatically preloaded with the IDCODE instruction at power-up whenever the controller is placed in test-logic-reset state.
Bypass register	The bypass register is a single bit register that can be placed between TDI and TDO. It allows serial test data to be passed through the RAMs TAP to another device in the scan chain with as little delay as possible.
ID register	The ID Register is a 32 bit register that is loaded with a device and vendor specific 32 bit code when the controller is put in capture-DR state with the IDCODE command loaded in the instruction register. The register is then placed between the TDI and TDO pins when the controller is moved into shift-DR state.
Boundary register	The boundary register, under the control of the TAP controller, is loaded with the contents of the RAMs I/O ring when the controller is in capture-DR state and then is placed between the TDI and TDO pins when the controller is moved to shift-DR state. Several TAP instructions can be used to activate the boundary register. The Scan Exit Order tables describe which device bump connects to each boundary register location. The first column defines the bit's position in the boundary register. The second column is the name of the input or I/O at the bump and the third column is the bump number.

Scan Register Definition (2)

Register name	Bit size	Unit
Instruction register	3	bit
Bypass register	1	bit
ID register	32	bit
Boundary register	107	bit

ID Register Definition

Part number	Organization	ID [31:28] vendor revision no.	ID [27:12] part no.	ID [11:1] vendor ID no.	ID [0] fix bit
μPD44164085A-A	2M x 8	XXXX	0000 0000 0001 1000	00000010000	1
μPD44164095A-A	2M x 9	XXXX	0000 0000 0101 0101	00000010000	1
μPD44164185A-A	1M x 18	XXXX	0000 0000 0001 1001	00000010000	1
μPD44164365A-A	512K x 36	XXXX	0000 0000 0001 1010	00000010000	1

SCAN Exit Order

Bit no.	Signal name x8	x9	x18	x36	Bump ID
1	C#				6R
2	C				6P
3	A				6N
4	A				7P
5	A				7N
6	A				7R
7	A				8R
8	A				8P
9	A				9R
10	NC	Q0	Q0	Q0	11P
11	NC	D0	D0	D0	10P
12	NC	NC	NC	D9	10N
13	NC	NC	NC	Q9	9P
14	NC	NC	Q1	Q1	10M
15	NC	NC	D1	D1	11N
16	NC	NC	NC	D10	9M
17	NC	NC	NC	Q10	9N
18	Q0	Q1	Q2	Q2	11L
19	D0	D1	D2	D2	11M
20	NC	NC	NC	D11	9L
21	NC	NC	NC	Q11	10L
22	NC	NC	Q3	Q3	11K
23	NC	NC	D3	D3	10K
24	NC	NC	NC	D12	9J
25	NC	NC	NC	Q12	9K
26	Q1	Q2	Q4	Q4	10J
27	D1	D2	D4	D4	11J
28	ZQ				11H
29	NC	NC	NC	D13	10G
30	NC	NC	NC	Q13	9G
31	NC	NC	Q5	Q5	11F
32	NC	NC	D5	D5	11G
33	NC	NC	NC	D14	9F
34	NC	NC	NC	Q14	10F
35	Q2	Q3	Q6	Q6	11E
36	D2	D3	D6	D6	10E

Bit no.	Signal name x8	X9	x18	x36	Bump ID
37	NC	NC	NC	D15	10D
38	NC	NC	NC	Q15	9E
39	NC	NC	Q7	Q7	10C
40	NC	NC	D7	D7	11D
41	NC	NC	NC	D16	9C
42	NC	NC	NC	Q16	9D
43	Q3	Q4	Q8	Q8	11B
44	D3	D4	D8	D8	11C
45	NC	NC	NC	D17	9B
46	NC	NC	NC	Q17	10B
47	CQ				11A
48	–				Internal
49	A	A	A	NC	9A
50	A				8B
51	A				7C
52	A				6C
53	LD#				8A
54	NC	NC	NC	BW1#	7A
55	NW0#	BW0#	BW0#	BW0#	7B
56	K				6B
57	K#				6A
58	NC	NC	NC	BW3#	5B
59	NW1#	NC	BW1#	BW2#	5A
60	R, W#				4A
61	A				5C
62	A				4B
63	A	A	NC	NC	3A
64	DLL#				1H
65	CQ#				1A
66	NC	NC	Q9	Q18	2B
67	NC	NC	D9	D18	3B
68	NC	NC	NC	D27	1C
69	NC	NC	NC	Q27	1B
70	NC	NC	Q10	Q19	3D
71	NC	NC	D10	D19	3C
72	NC	NC	NC	D28	1D

Bit no.	Signal name x8	X9	x18	x36	Bump ID
73	NC	NC	NC	Q28	2C
74	Q4	Q5	Q11	Q20	3E
75	D4	D5	D11	D20	2D
76	NC	NC	NC	D29	2E
77	NC	NC	NC	Q29	1E
78	NC	NC	Q12	Q21	2F
79	NC	NC	D12	D21	3F
80	NC	NC	NC	D30	1G
81	NC	NC	NC	Q30	1F
82	Q5	Q6	Q13	Q22	3G
83	D5	D6	D13	D22	2G
84	NC	NC	NC	D31	1J
85	NC	NC	NC	Q31	2J
86	NC	NC	Q14	Q23	3K
87	NC	NC	D14	D23	3J
88	NC	NC	NC	D32	2K
89	NC	NC	NC	Q32	1K
90	Q6	Q7	Q15	Q24	2L
91	D6	D7	D15	D24	3L
92	NC	NC	NC	D33	1M
93	NC	NC	NC	Q33	1L
94	NC	NC	Q16	Q25	3N
95	NC	NC	D16	D25	3M
96	NC	NC	NC	D34	1N
97	NC	NC	NC	Q34	2M
98	Q7	Q8	Q17	Q26	3P
99	D7	D8	D17	D26	2N
100	NC	NC	NC	D35	2P
101	NC	NC	NC	Q35	1P
102	A				3R
103	A				4R
104	A				4P
105	A				5P
106	A				5N
107	A				5R

JTAG Instructions

Instructions	Description
EXTEST	The EXTEST instruction allows circuitry external to the component package to be tested. Boundary-scan register cells at output pins are used to apply test vectors, while those at input pins capture test results. Typically, the first test vector to be applied using the EXTEST instruction will be shifted into the boundary scan register using the PRELOAD instruction. Thus, during the update-IR state of EXTEST, the output drive is turned on and the PRELOAD data is driven onto the output pins.
IDCODE	The IDCODE instruction causes the ID ROM to be loaded into the ID register when the controller is in capture-DR mode and places the ID register between the TDI and TDO pins in shift-DR mode. The IDCODE instruction is the default instruction loaded in at power up and any time the controller is placed in the test-logic-reset state.
BYPASS	When the BYPASS instruction is loaded in the instruction register, the bypass register is placed between TDI and TDO. This occurs when the TAP controller is moved to the shift-DR state. This allows the board level scan path to be shortened to facilitate testing of other devices in the scan path.
SAMPLE / PRELOAD	SAMPLE / PRELOAD is a Standard 1149.1 mandatory public instruction. When the SAMPLE / PRELOAD instruction is loaded in the instruction register, moving the TAP controller into the capture-DR state loads the data in the RAMs input and Q pins into the boundary scan register. Because the RAM clock(s) are independent from the TAP clock (TCK) it is possible for the TAP to attempt to capture the I/O ring contents while the input buffers are in transition (i.e., in a metastable state). Although allowing the TAP to sample metastable input will not harm the device, repeatable results cannot be expected. RAM input signals must be stabilized for long enough to meet the TAPs input data capture setup plus hold time (t_{CS} plus t_{CH}). The RAMs clock inputs need not be paused for any other TAP operation except capturing the I/O ring contents into the boundary scan register. Moving the controller to shift-DR state then places the boundary scan register between the TDI and TDO pins.
SAMPLE-Z	If the SAMPLE-Z instruction is loaded in the instruction register, all RAM Q pins are forced to an inactive drive state (high impedance) and the boundary register is connected between TDI and TDO when the TAP controller is moved to the shift-DR state.

JTAG Instruction Coding

IR2	IR1	IR0	Instruction	Note
0	0	0	EXTEST	
0	0	1	IDCODE	
0	1	0	SAMPLE-Z	1
0	1	1	RESERVED	2
1	0	0	SAMPLE / PRELOAD	
1	0	1	RESERVED	2
1	1	0	RESERVED	2
1	1	1	BYPASS	

Notes 1. TRISTATE all Q pins and CAPTURE the pad values into a SERIAL SCAN LATCH.

2. Do not use this instruction code because the vendor uses it to evaluate this product.

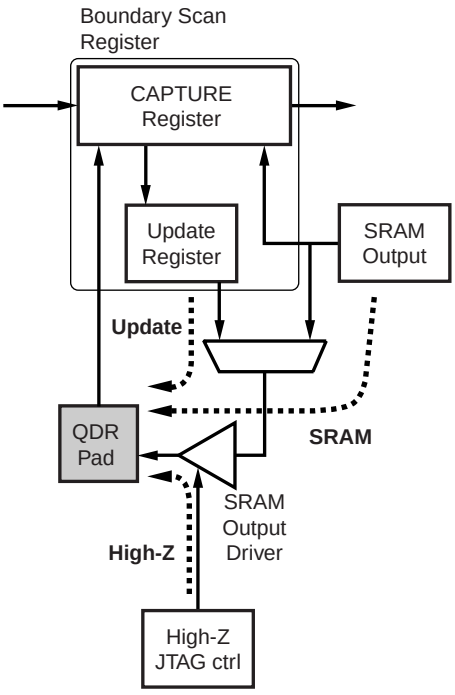
Output Pin States of CQ, CQ# and Q

Instructions	Control-Register Status	Output Pin Status	
		CQ, CQ#	Q
EXTEST	0	Update	High-Z
	1	Update	Update
IDCODE	0	SRAM	SRAM
	1	SRAM	SRAM
SAMPLE-Z	0	High-Z	High-Z
	1	High-Z	High-Z
SAMPLE	0	SRAM	SRAM
	1	SRAM	SRAM
BYPASS	0	SRAM	SRAM
	1	SRAM	SRAM

Remark The output pin statuses during each instruction vary according to the Control-Register status (value of Boundary Scan Register, bit no. 48).
There are three statuses:

Update : Contents of the “Update Register” are output to the output pin (QDR Pad).
SRAM : Contents of the SRAM internal output “SRAM Output” are output to the output pin (QDR Pad).
High-Z : The output pin (QDR Pad) becomes high impedance by controlling of the “High-Z JTAG ctrl”.

The Control-Register status is set during Update-DR at the EXTEST or SAMPLE instruction.



Boundary Scan Register Status of Output Pins CQ, CQ# and Q

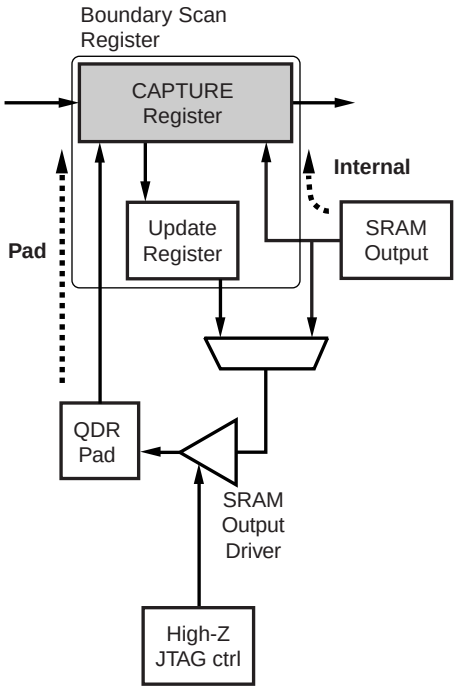
Instructions	SRAM Status	Boundary Scan Register Status		Note
		CQ, CQ#	Q	
EXTEST	READ (Low-Z)	Pad	Pad	
	NOP (High-Z)	Pad	Pad	
IDCODE	READ (Low-Z)	–	–	No definition
	NOP (High-Z)	–	–	
SAMPLE-Z	READ (Low-Z)	Pad	Pad	
	NOP (High-Z)	Pad	Pad	
SAMPLE	READ (Low-Z)	Internal	Internal	
	NOP (High-Z)	Internal	Pad	
BYPASS	READ (Low-Z)	–	–	No definition
	NOP (High-Z)	–	–	

Remark The Boundary Scan Register statuses during execution each instruction vary according to the instruction code and SRAM operation mode.

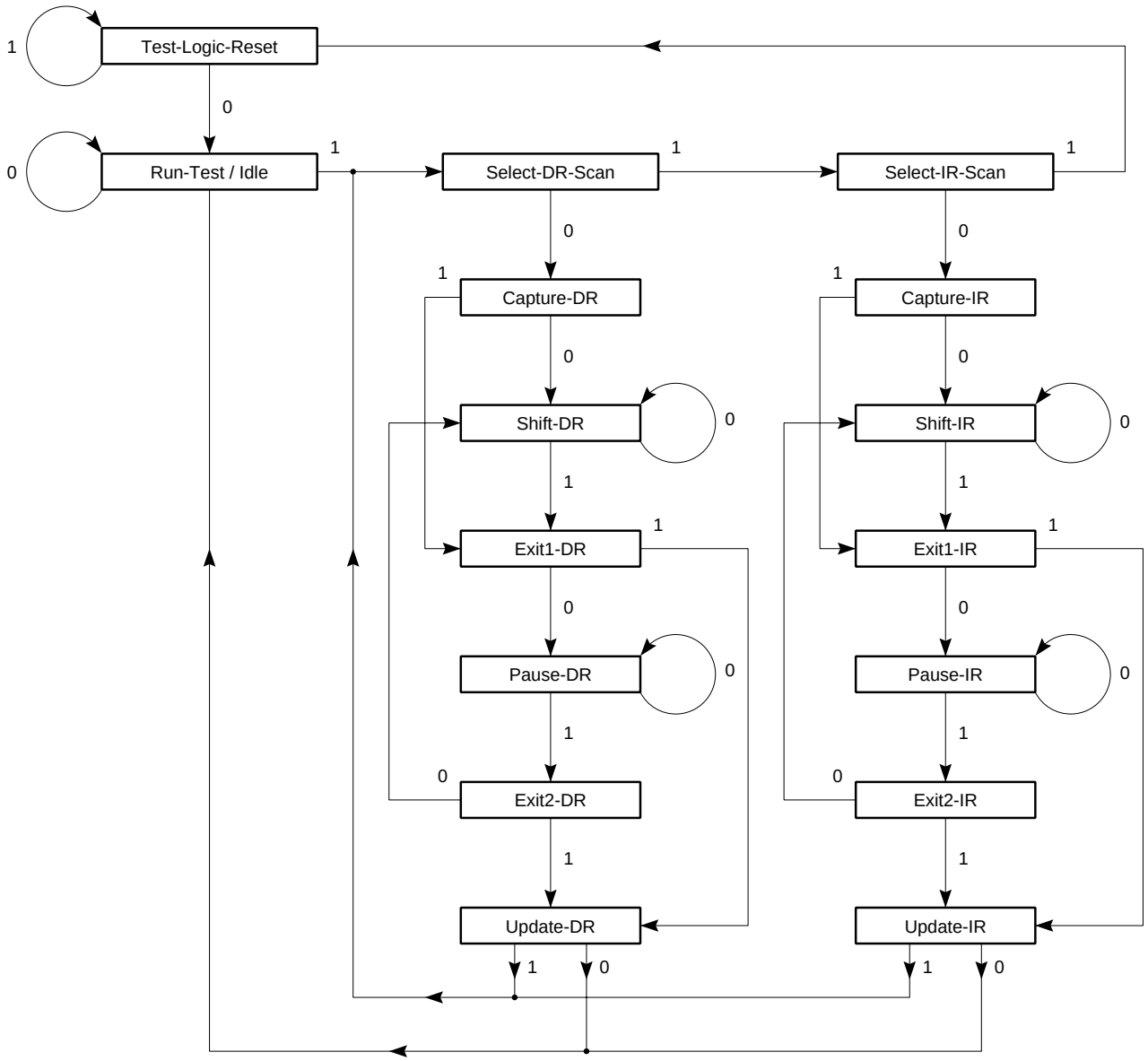
There are two statuses:

Pad : Contents of the output pin (QDR Pad) are captured in the "CAPTURE Register" in the Boundary Scan Register.

Internal : Contents of the SRAM internal output "SRAM Output" are captured in the "CAPTURE Register" in the Boundary Scan Register.



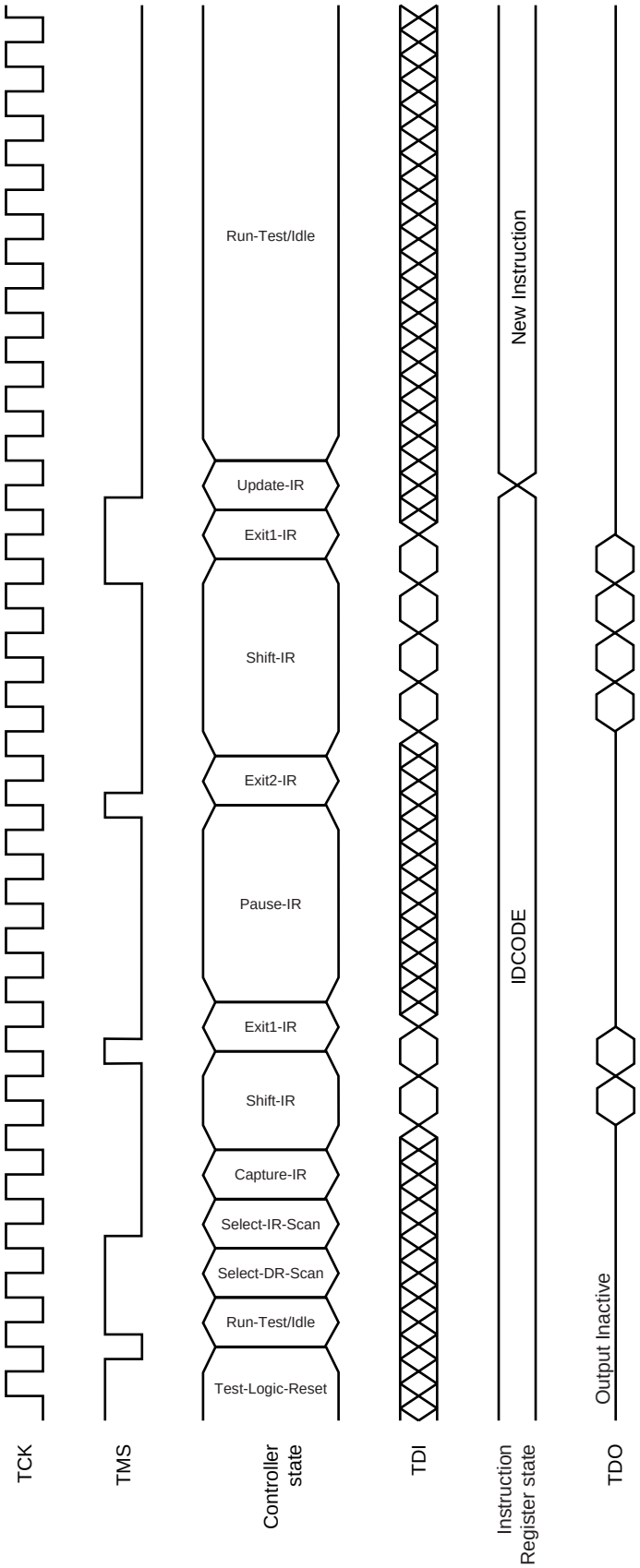
TAP Controller State Diagram



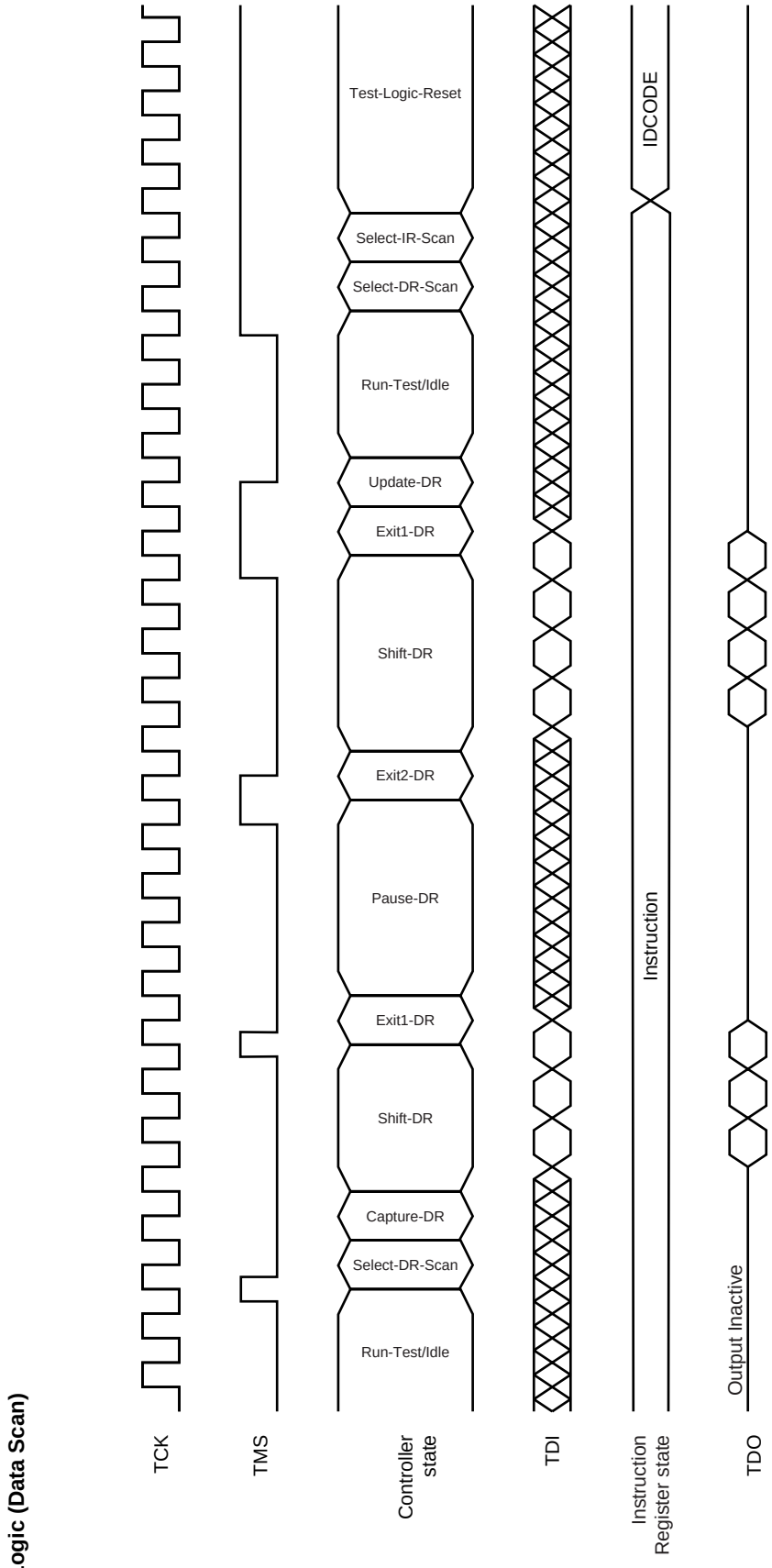
Disabling the Test Access Port

It is possible to use this device without utilizing the TAP. To disable the TAP Controller without interfering with normal operation of the device, TCK must be tied to V_{SS} to preclude mid level inputs. TDI and TMS may be left open but fix them to V_{DD} via a resistor of about 1 kΩ when the TAP controller is not used. TDO should be left unconnected also when the TAP controller is not used.

Test Logic Operation (Instruction Scan)

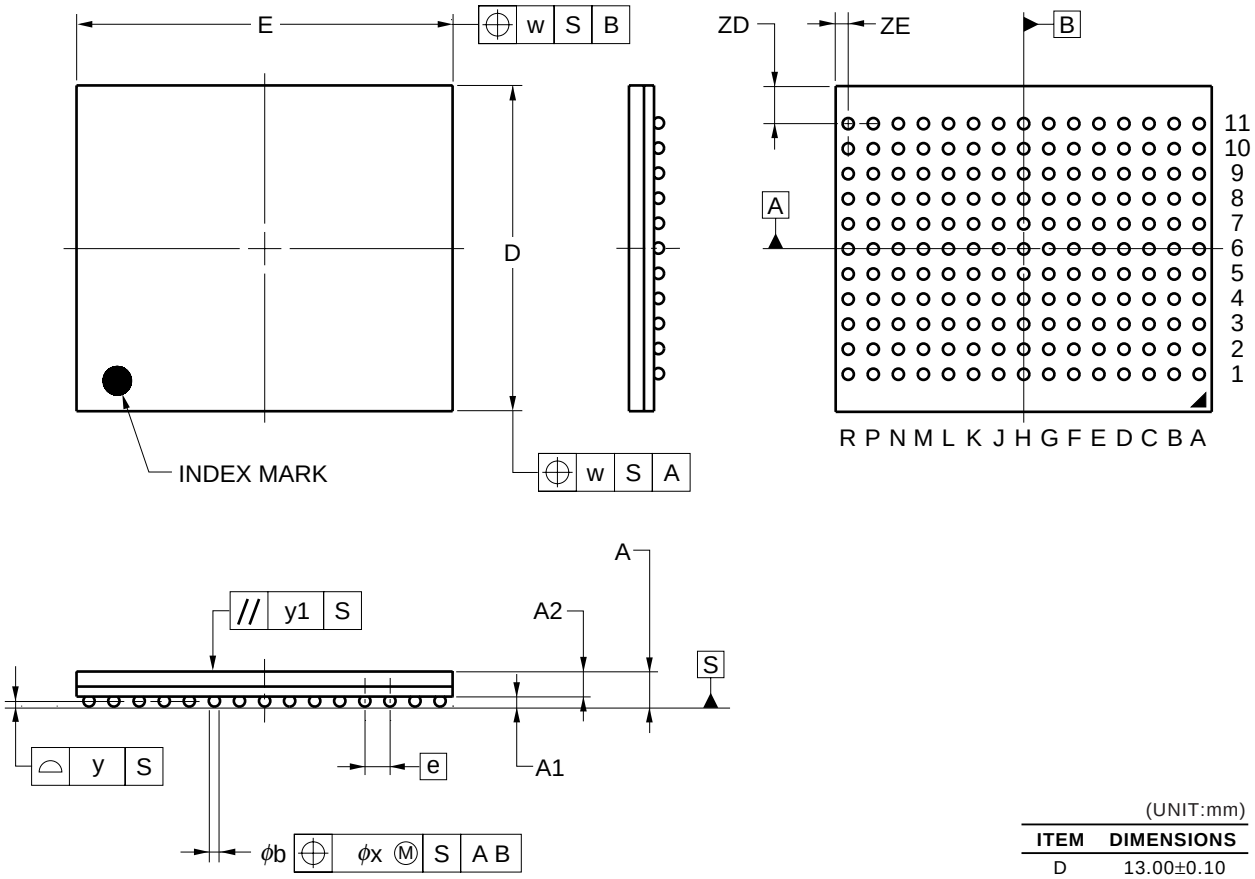


Test Logic (Data Scan)



Package Drawing

165-PIN PLASTIC BGA (13x15)



(UNIT:mm)

ITEM	DIMENSIONS
D	13.00±0.10
E	15.00±0.10
w	0.15
e	1.00
A	1.40±0.11
A1	0.40±0.05
A2	1.00
b	0.50±0.05
x	0.08
y	0.10
y1	0.20
ZD	1.50
ZE	0.50

P165F5-100-EQ2

Recommended Soldering Condition

Please consult with our sales offices for soldering conditions of these products.

Types of Surface Mount Devices

μPD44164085AF5-EQ2-A : 165-pin PLASTIC BGA (13 x 15)
μPD44164095AF5-EQ2-A : 165-pin PLASTIC BGA (13 x 15)
μPD44164185AF5-EQ2-A : 165-pin PLASTIC BGA (13 x 15)
μPD44164365AF5-EQ2-A : 165-pin PLASTIC BGA (13 x 15)

Quality Grade

- A quality grade of the products is “Standard”.
- Anti-radioactive design is not implemented in the products.
- Semiconductor devices have the possibility of unexpected defects by affection of cosmic ray that reach to the ground and so forth.

[MEMO]

NOTES FOR CMOS DEVICES

① VOLTAGE APPLICATION WAVEFORM AT INPUT PIN

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (MAX) and V_{IH} (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (MAX) and V_{IH} (MIN).

② HANDLING OF UNUSED INPUT PINS

Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

③ PRECAUTION AGAINST ESD

A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

④ STATUS BEFORE INITIALIZATION

Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

⑤ POWER ON/OFF SEQUENCE

In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current.

The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

⑥ INPUT OF SIGNAL DURING POWER OFF STATE

Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements.

Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.

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